

ABSTRACT

An improved probe card and needle assemblage for electrically contacting and testing integrated circuit wafers minimizes damage to metallization on chip pads, and reduces probe card maintenance and repair. The improved probe needle assemblage includes both a primary and secondary spring mechanism which allows the needle tip to adjust to differences in height between probes, thereby not only minimizing damage, but also simplifying probe card fabrication. The improved probe needle assemblage is compatible with probe cards and automated test equipment of known art.

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